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INCOMING INSPECTION 1 DAY

Course Description

Hybrids/MCMs/RF Modules all require a visual inspection at various points throughout the manufacturing process flow. Incoming visual inspection is a critical process step that requires a high degree of operator skill and understanding of what to look for and reject as part of the inspection process. Silicon wafer fabrication processes are explored in detail along with thick and thin film substrate processing. Color photographs of actual production defects are reviewed and discussed. Students will understand the basic fabrication processes and the typical kinds of defects that result from poorly controlled processes

The course is intended for quality assurance personnel, inspectors, lead operators and others responsible for inspection of the hardware prior to the final package sealing process.

Course Outline

CLASSROOM LECTURE (DAY 1)

Hybrid Materials and Processing Overview
Review of Terminology
Wafer Fabrication Processes
 Silicon fabrication technology
Thick Film Substrates
Thin Film Processes

Incoming Inspection

- Defects related to wafer fab, saw and break, probe test, etc.
- Thick Film/Thin Film substrate defects
- Laser trim defects
- Passive components

Summary
Student Feedback

Course Fee: \$695